Preferred Devices

# **Surface Mount Ultrafast Power Rectifiers**

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

#### **Features**

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.66 V Max @ 1.0 A,  $T_J = 150^{\circ}\text{C}$ )
- Pb-Free Packages are Available

## **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Protection: Human Body Model > 4000 V (Class 3) Machine Model > 400 V (Class C)

# **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage MURA105T3 MURA110T3	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	50 100	<b>&gt;</b>
Average Rectified Forward Current @ T <sub>L</sub> = 155°C @ T <sub>L</sub> = 135°C	I <sub>F(AV)</sub>	1.0 2.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	50	Α
Operating Junction Temperature Range	TJ	-65 to +175	°C

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Lead (Note 1) Thermal Resistance, Junction-to-Ambient (Note 1)	Psi <sub>JL</sub> (Note 2) R <sub>θJA</sub>	24 216	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- Rating applies when surface mounted on the minimum pad size recommended, PC Board FR-4.
- 2. In compliance with JEDEC 51, these values (historically represented by  $R_{\theta JL}$ ) are now referenced as  $Psi_{JL}$ .



# ON Semiconductor®

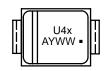
http://onsemi.com

# **ULTRAFAST RECTIFIERS**1 AMPERE, 50–100 VOLTS



SMA CASE 403D PLASTIC

## **MARKING DIAGRAM**



U4x = Device Code

x = A for MURA105T3 = B for MURA110T3

A = Assembly Location

Y = Year WW = Work Week Pb-Free Package

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MURA105T3	SMA	5000/Tape & Reel
MURA105T3G	SMA (Pb-Free)	5000/Tape & Reel
MURA110T3	SMA	5000/Tape & Reel
MURA110T3G	SMA (Pb-Free)	5000/Tape & Reel

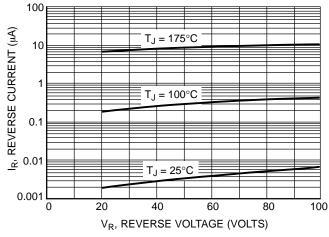
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

# **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (Note 3) ( $i_F = 1.0 \text{ A}, T_J = 25^{\circ}\text{C}$ ) ( $i_F = 1.0 \text{ A}, T_J = 150^{\circ}\text{C}$ )	VF	0.875 0.66	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 25^{\circ}C$ ) (Rated dc Voltage, $T_J = 150^{\circ}C$ )	İR	2.0 50	μΑ
Maximum Reverse Recovery Time (i <sub>F</sub> = 1.0 A, di/dt = 50 A/ $\mu$ s)	t <sub>rr</sub>	30	ns

<sup>3.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.



**Figure 1. Typical Reverse Current** 

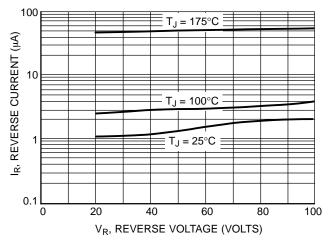


Figure 2. Maximum Reverse Current

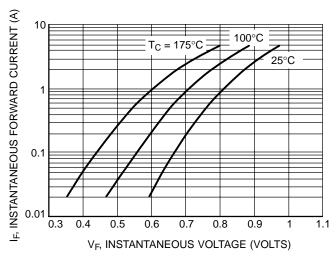


Figure 3. Typical Forward Voltage

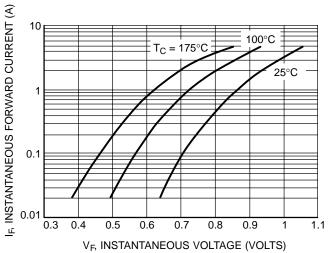


Figure 4. Maximum Forward Voltage

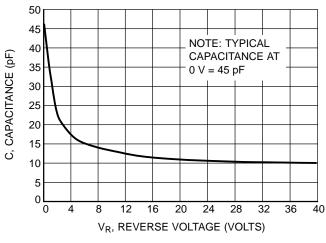


Figure 5. Typical Capacitance

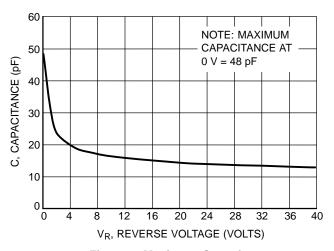


Figure 6. Maximum Capacitance

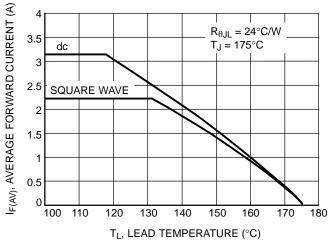


Figure 7. Current Derating, Lead

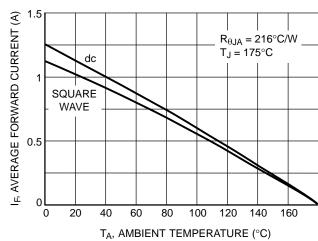


Figure 8. Current Derating, Ambient (FR-4 Board with Minimum Pad)

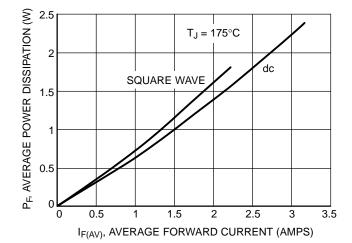
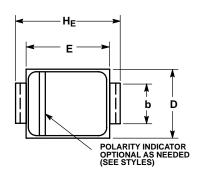


Figure 9. Power Dissipation

# PACKAGE DIMENSIONS

# **SMA** CASE 403D-02 **ISSUE C**



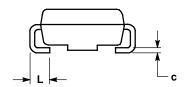


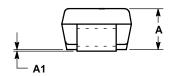
- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
  3. 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.91	2.16	2.41	0.075	0.085	0.095
A1	0.05	0.10	0.15	0.002	0.004	0.006
b	1.27	1.45	1.63	0.050	0.057	0.064
С	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
HE	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060

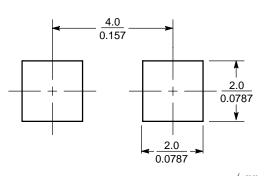
STYLE 1: PIN 1. CATHODE (POLARITY BAND)

2. ANODE





## **SOLDERING FOOTPRINT\***



 $\left(\frac{mm}{inches}\right)$ SCALE 8:1

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MURA105T3/D

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.